



Bill of Materials

TI DESIGNS

TIDM-1WIREEPROM

Item	Qty	Reference/Designator	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	Altium Footprint
1	1	C1	22uF	CAP, AL, 22uF, 25V, +/-20%, TH	Panasonic	20SEP22M		ML_500x500
2	1	D1		Diode, Schottky, 800mA, 30V, SM	Toshiba	CUS08F30, H3F		SOD-323
3	1	J1		Header, 100mil, 3x1, Tin, TH	Würth Electronics	61300311121		5-146278-3
4	1	J2		Header, 100mil, 15x1, Tin, TH	Samtec	SSW-115-23-F-S		Custom
5	1	R1	1.00k	RES, 1.00k ohm, 1%, 0.25W, TH	Stackpole Electronics	CF14JT1K00		CMF50

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